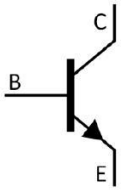
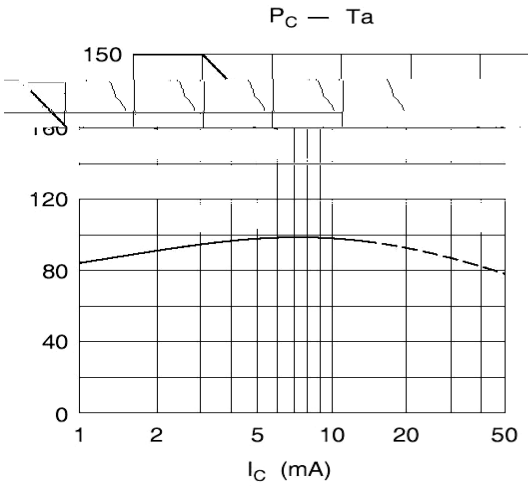
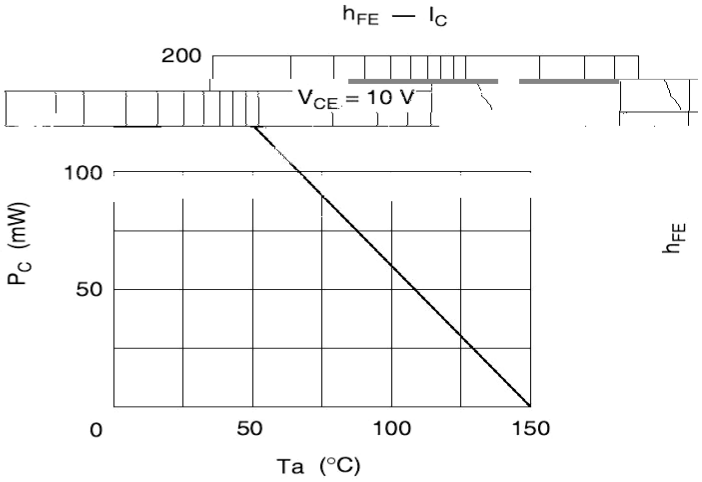
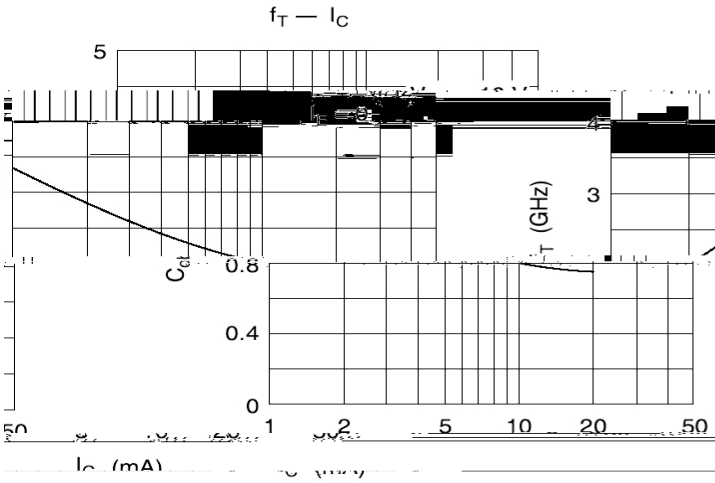

C
B
E

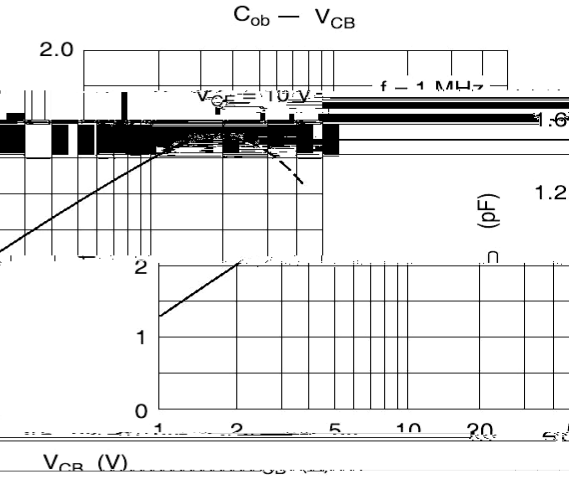
			℃
			℃

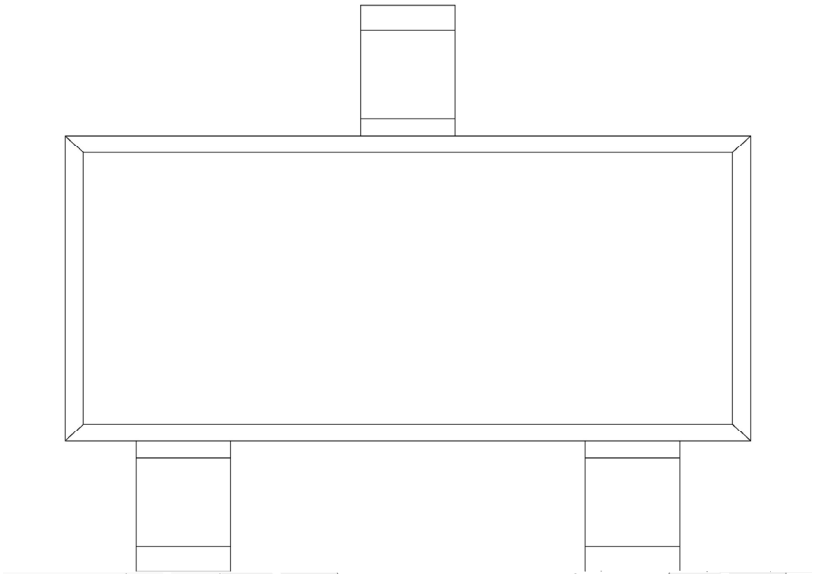
		μ				
		∞				
		μ				
						μ
						μ


P_C — Ta
150
120
80
40
0
1
2
5
10
20
50
I_C (mA)

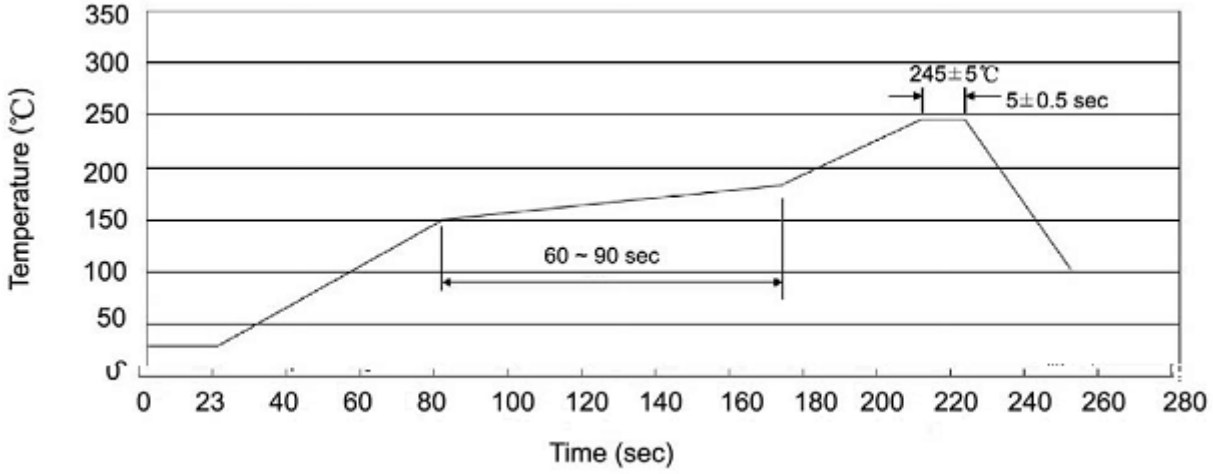

h_{FE} — I_C
200
V_{CE} = 10 V
100
50
0
P_C (mW)
50
100
150
Ta (°C)
h_{FE}


f_T — I_C
5
3
0.8
0.4
0
1
2
5
10
20
50
f_T (GHz)


C_{ob} — V_{CB}
2.0
1.2
2
1
0
1
2
5
10
20
(pF)
V_{CB} (V)



Temperature Profile for IR Reflow Soldering(Pb-Free)



℃

封装形式	包装数量					包装尺寸 :		
	只卷盘	卷盘盒	只盒	盒箱	只箱		盒	箱